

# BCR16PM-14LG

Triac

Medium Power Use

REJ03G1675-0100

Rev.1.00

Jun 04, 2008

## Features

- $I_{T(RMS)}$  : 16 A
- $V_{DRM}$  : 800 V
- $I_{FGTL}, I_{RGTL}, I_{RGT III}$  : 30 mA
- $V_{iso}$  : 2000V
- The Product guaranteed maximum junction temperature 150°C
- Insulated Type
- Planar Type
- UL Recognized : Yellow Card No. E223904  
File No.E80271

## Outline

RENESAS Package code: PRSS0003AA-A  
(Package name: TO-220F)



1. T<sub>1</sub> Terminal
2. T<sub>2</sub> Terminal
3. Gate Terminal

## Applications

Washing machine, inversion operation of capacitor motor, and other general controlling devices.

## Maximum Ratings

Parameter	Symbol	Voltage class	Unit	Condition
		14		
Repetitive peak off-state voltage <sup>Note1</sup>	$V_{DRM}$	800	V	T <sub>j</sub> = 125°C
		700	V	T <sub>j</sub> = 150°C
Non-repetitive peak off-state voltage <sup>Note1</sup>	$V_{DSM}$	840	V	

Notes: 1. Gate open.

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_{T(RMS)}$	16	A	Commercial frequency, sine full wave 360° conduction, $T_c = 87^\circ\text{C}$
Surge on-state current	$I_{TSM}$	160	A	60 Hz sinewave 1 full cycle, peak value, non-repetitive
$I^2t$ for fusion	$I^2t$	106.5	$\text{A}^2\text{s}$	Value corresponding to 1 cycle of half wave 60 Hz, surge on-state current
Peak gate power dissipation	$P_{GM}$	5	W	
Average gate power dissipation	$P_{G(AV)}$	0.5	W	
Peak gate voltage	$V_{GM}$	10	V	
Peak gate current	$I_{GM}$	2	A	
Junction Temperature	$T_j$	-40 to +150	$^\circ\text{C}$	
Storage temperature	$T_{stg}$	-40 to +150	$^\circ\text{C}$	
Mass	—	2.0	g	Typical value
Isolation voltage	$V_{iso}$	2000	V	$T_a = 25^\circ\text{C}$ , AC 1 minute, $T_1 \cdot T_2 \cdot G$ terminal to case

Notes: 1. Gate open.

## Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Repetitive peak off-state current	$I_{DRM}$	—	—	5.0	mA	$T_j = 150^\circ\text{C}$ , $V_{DRM}$ applied
On-state voltage	$V_{TM}$	—	—	1.5	V	$T_c = 25^\circ\text{C}$ , $I_{TM} = 25\text{ A}$ , instantaneous measurement
Gate trigger voltage <sup>Note2</sup>	I	$V_{FGTI}$	—	—	1.5	$T_j = 25^\circ\text{C}$ , $V_D = 6\text{ V}$ , $R_L = 6\ \Omega$ , $R_G = 330\ \Omega$
	II	$V_{RGTI}$	—	—	1.5	
	III	$V_{RGTIII}$	—	—	1.5	
Gate trigger current <sup>Note2</sup>	I	$I_{FGTI}$	—	—	30	$T_j = 25^\circ\text{C}$ , $V_D = 6\text{ V}$ , $R_L = 6\ \Omega$ , $R_G = 330\ \Omega$
	II	$I_{RGTI}$	—	—	30	
	III	$I_{RGTIII}$	—	—	30	
Gate non-trigger voltage	$V_{GD}$	0.2/0.1	—	—	V	$T_j = 125^\circ\text{C}/150^\circ\text{C}$ , $V_D = 1/2 V_{DRM}$
Thermal resistance	$R_{th(j-c)}$	—	—	3.5	$^\circ\text{C}/\text{W}$	Junction to case <sup>Note3</sup>
Critical-rate of rise of off-state commutation voltage <sup>Note4</sup>	$(dv/dt)_c$	10/1	—	—	$\text{V}/\mu\text{s}$	$T_j = 125^\circ\text{C}/150^\circ\text{C}$

Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

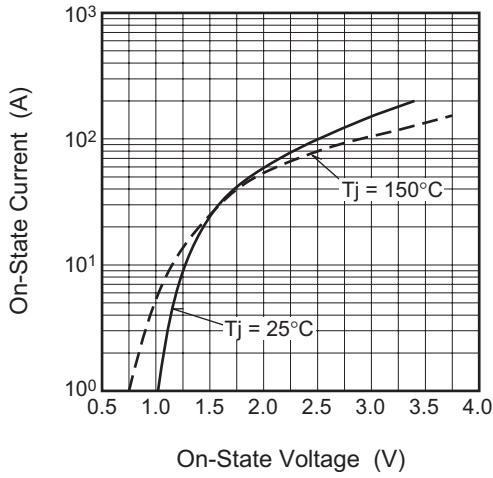
3. The contact thermal resistance  $R_{th(c-f)}$  in case of greasing is  $0.5^\circ\text{C}/\text{W}$ .

4. Test conditions of the critical-rate of rise of off-state commutation voltage is shown in the table below.

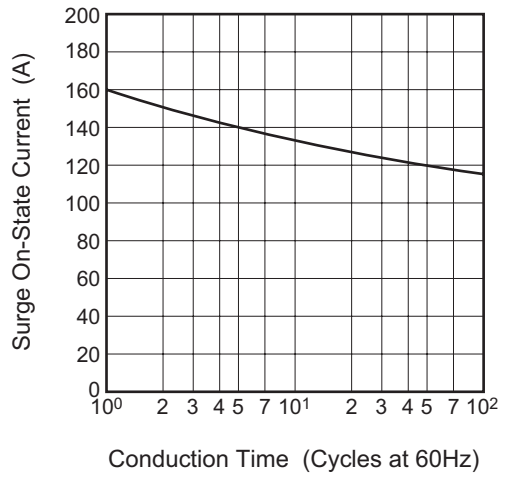
Test conditions	Commutating voltage and current waveforms (inductive load)
1. Junction temperature $T_j = 125^\circ\text{C}/150^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_c = -8.0\text{ A/ms}$ 3. Peak off-state voltage $V_D = 400\text{ V}$	

Performance Curves

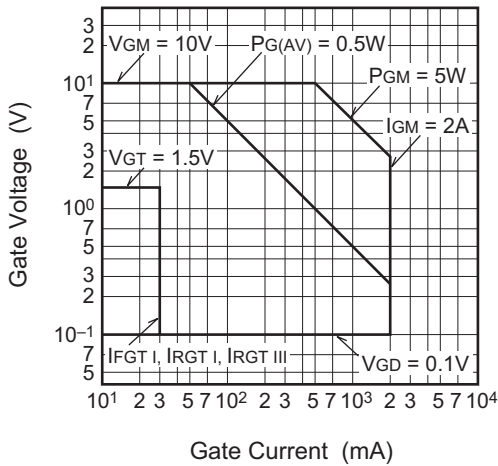
Maximum On-State Characteristics



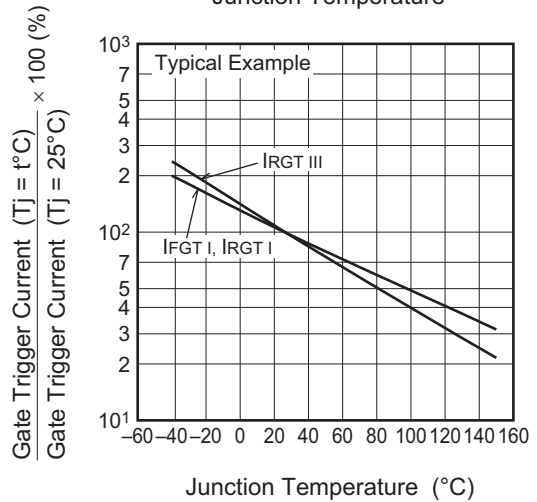
Rated Surge On-State Current



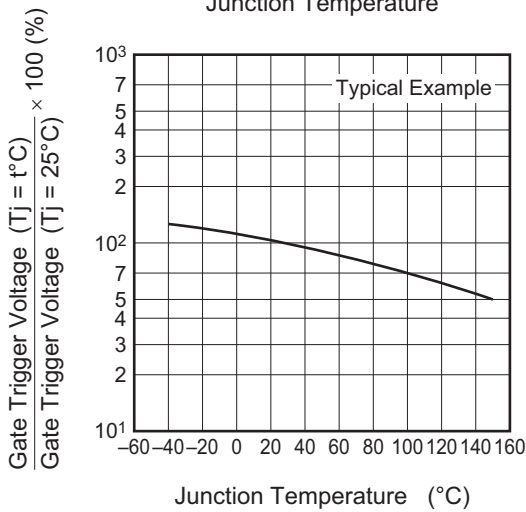
Gate Characteristics (I, II and III)



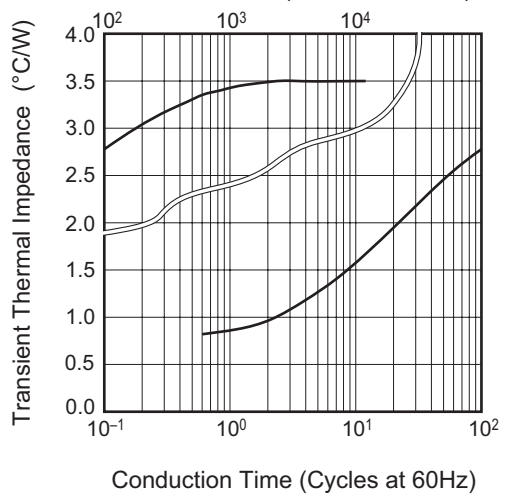
Gate Trigger Current vs. Junction Temperature



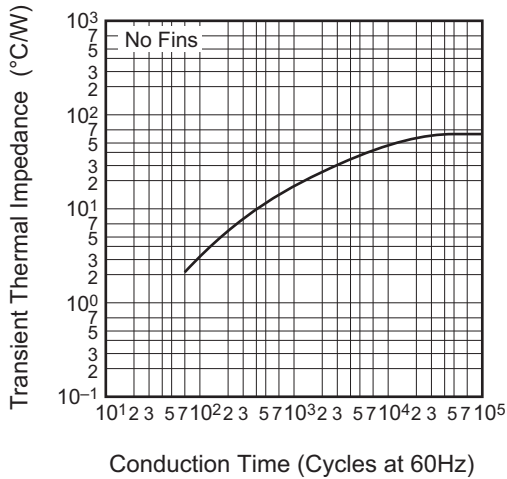
Gate Trigger Voltage vs. Junction Temperature



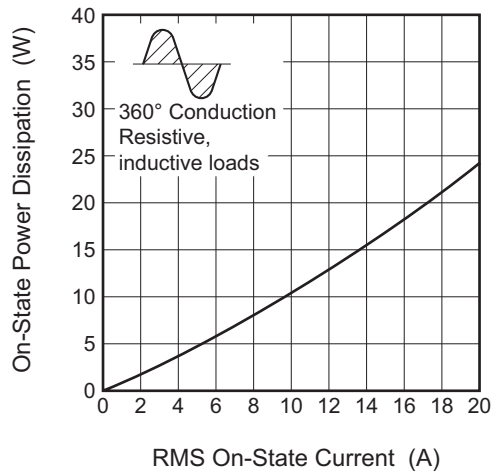
Maximum Transient Thermal Impedance Characteristics (Junction to case)



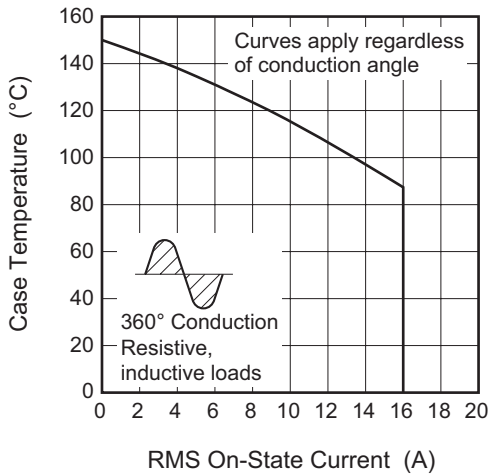
Maximum Transient Thermal Impedance Characteristics (Junction to ambient)



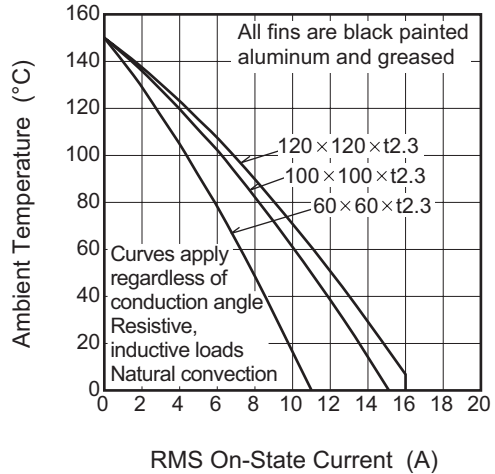
Maximum On-State Power Dissipation



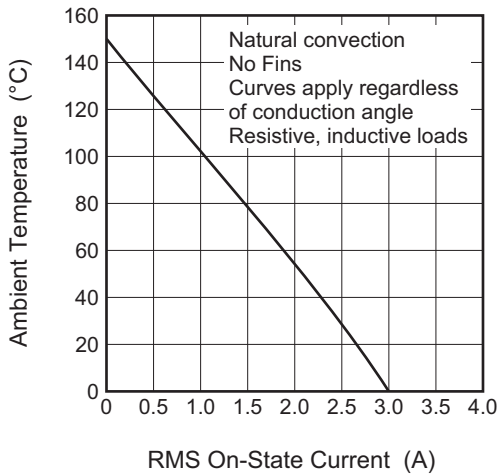
Allowable Case Temperature vs. RMS On-State Current



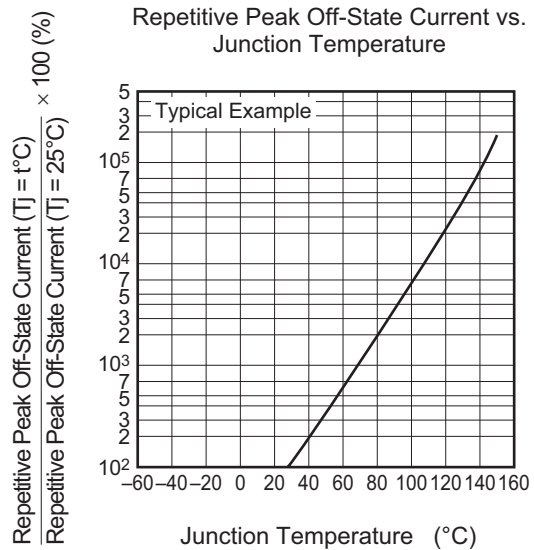
Allowable Ambient Temperature vs. RMS On-State Current



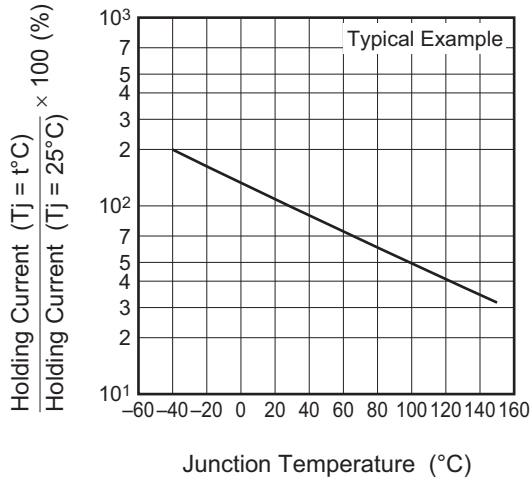
Allowable Ambient Temperature vs. RMS On-State Current



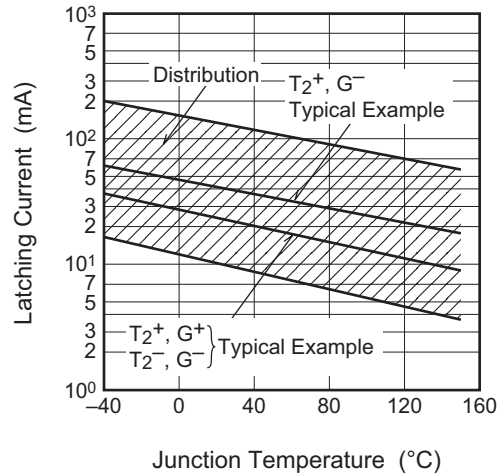
Repetitive Peak Off-State Current vs. Junction Temperature



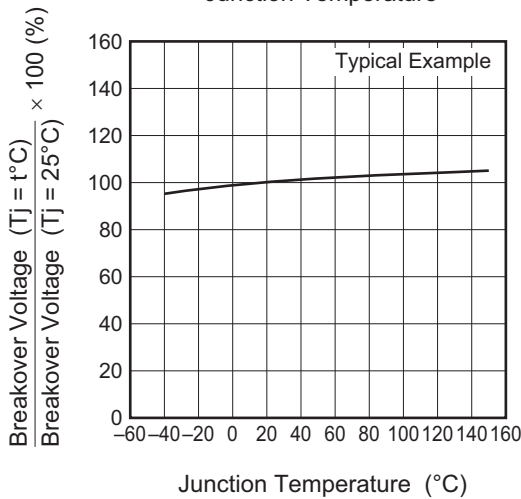
Holding Current vs. Junction Temperature



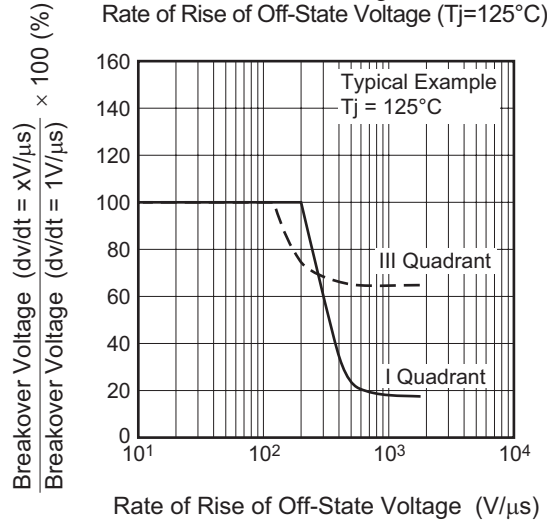
Latching Current vs. Junction Temperature



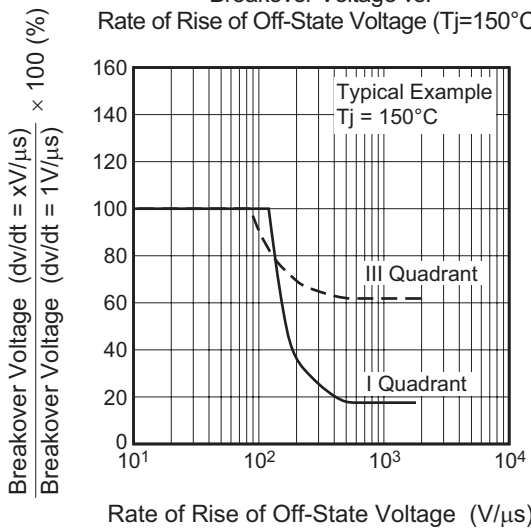
Breakover Voltage vs. Junction Temperature



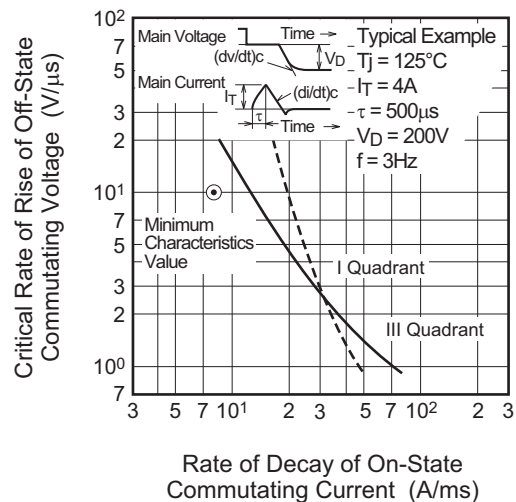
Breakover Voltage vs. Rate of Rise of Off-State Voltage (Tj=125°C)



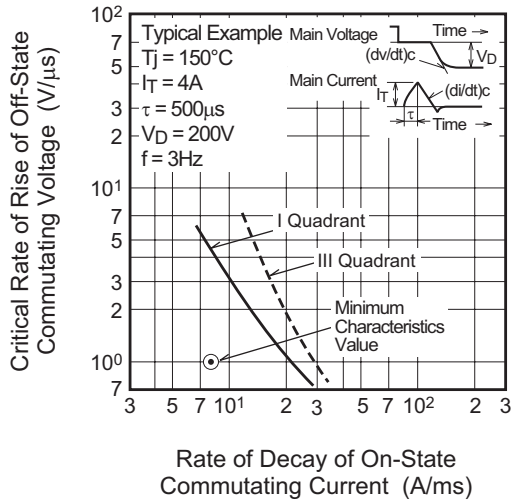
Breakover Voltage vs. Rate of Rise of Off-State Voltage (Tj=150°C)



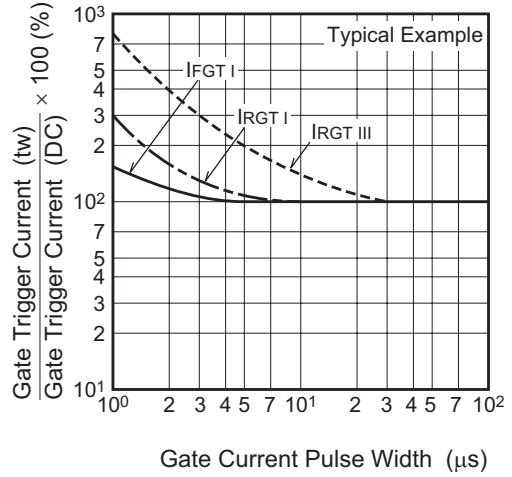
Commutation Characteristics (Tj=125°C)



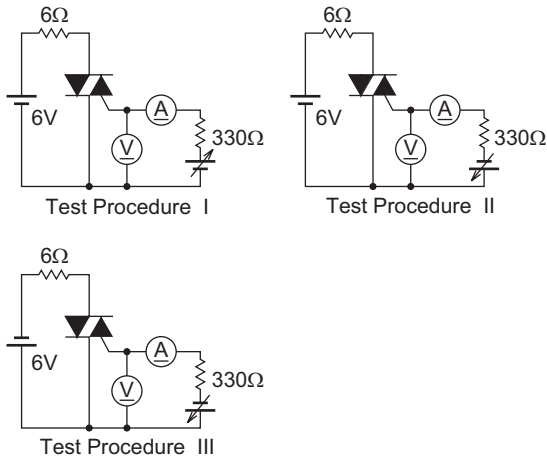
Commutation Characteristics (Tj=150°C)



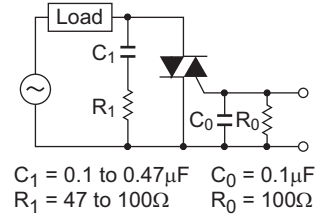
Gate Trigger Current vs. Gate Current Pulse Width



Gate Trigger Characteristics Test Circuits



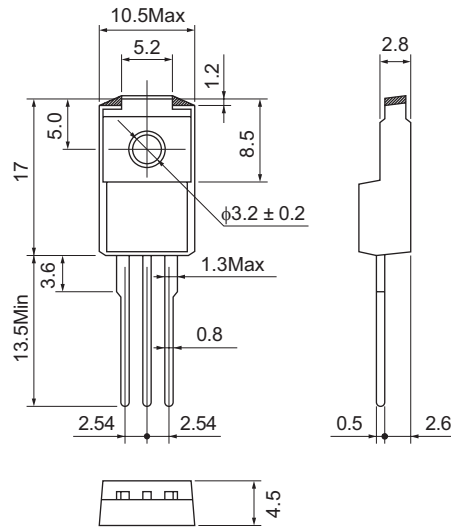
Recommended Circuit Values Around The Triac



Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
TO-220F	SC-67	PRSS0003AA-A	—	2.0g

Unit: mm



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	100	Type name	BCR16PM-14LG
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	BCR16PM-14LG-A8

Note : Please confirm the specification about the shipping in detail.

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Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

**Renesas Technology Europe Limited**  
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.  
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

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Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120  
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10th Floor, No.99, Fushing North Road, Taipei, Taiwan  
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1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632  
Tel: <65> 6213-0200, Fax: <65> 6278-8001

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Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea  
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

**Renesas Technology Malaysia Sdn. Bhd**  
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia  
Tel: <603> 7955-9390, Fax: <603> 7955-9510